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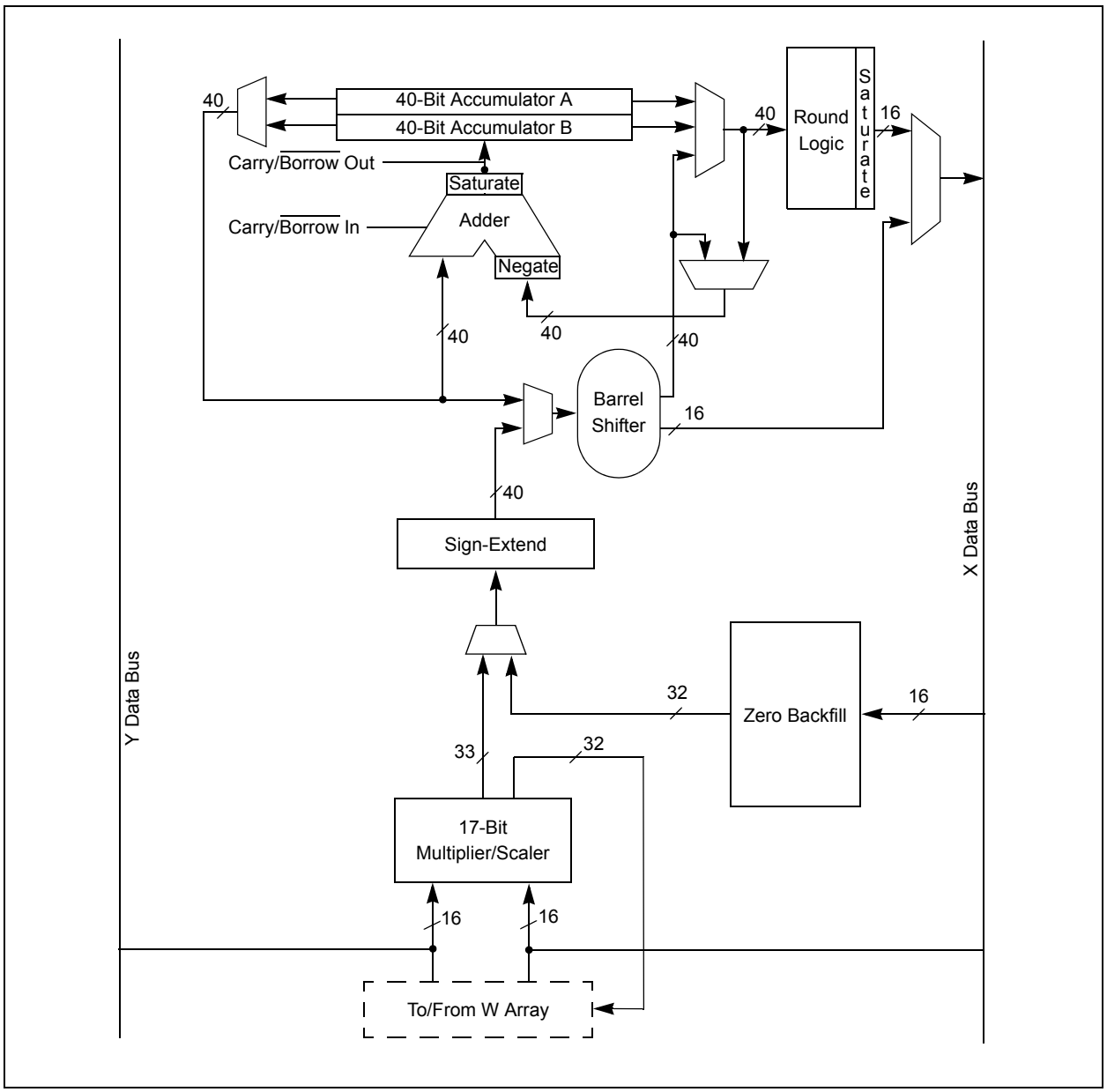
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	6KB (2K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj06gs001-e-ss

FIGURE 3-3: DSP ENGINE BLOCK DIAGRAM



4.2.5 X AND Y DATA SPACES

The core has two data spaces, X and Y. These data spaces can be considered either separate (for some DSP instructions), or as one unified linear address range (for MCU instructions). The data spaces are accessed using two Address Generation Units (AGUs) and separate data paths. This feature allows certain instructions to concurrently fetch two words from RAM, thereby enabling efficient execution of DSP algorithms, such as Finite Impulse Response (FIR) filtering and Fast Fourier Transform (FFT).

The X data space is used by all instructions and supports all addressing modes. X data space has separate read and write data buses. The X read data bus is the read data path for all instructions that view data space as combined X and Y address space. It is also the X data prefetch path for the dual operand DSP instructions (`MAC` class).

The Y data space is used in concert with the X data space by the `MAC` class of instructions (`CLR`, `ED`, `EDAC`, `MAC`, `MOVSAC`, `MPY`, `MPY.N` and `MSC`) to provide two concurrent data read paths.

Both the X and Y data spaces support Modulo Addressing mode for all instructions, subject to addressing mode restrictions. Bit-Reversed Addressing mode is only supported for writes to X data space.

All data memory writes, included in DSP instructions, view data space as combined X and Y address space. The boundary between the X and Y data spaces is device-dependent and is not user-programmable.

All Effective Addresses are 16 bits wide and point to bytes within the data space. Therefore, the data space address range is 64 Kbytes, or 32K words, though the implemented memory locations vary by device.

TABLE 4-7: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC33FJ06GS202A DEVICES ONLY

File Name	SFR Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
INTCON1	0080	NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE	SFTACERR	DIV0ERR	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—	0000
INTCON2	0082	ALTIVT	DISI	—	—	—	—	—	—	—	—	—	—	—	INT2EP	INT1EP	INT0EP	0000
IFS0	0084	—	—	ADIF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	—	T2IF	—	—	—	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0086	—	—	INT2IF	—	—	—	—	—	—	—	—	INT1IF	CNIF	AC1IF	MI2C1IF	SI2C1IF	0000
IFS3	008A	—	—	—	—	—	—	PSEMIF	—	—	—	—	—	—	—	—	—	0000
IFS4	008C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	U1EIF	—	0000
IFS5	008E	PWM2IF	PWM1IF	—	—	—	—	—	—	—	—	—	—	—	—	—	JTAGIF	0000
IFS6	0090	ADCP1IF	ADCP0IF	—	—	—	—	—	—	AC2IF	—	—	—	—	—	—	—	0000
IFS7	0092	—	—	—	—	—	—	—	—	—	—	—	ADCP6IF	—	—	—	ADCP2IF	0000
IEC0	0094	—	—	ADIE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	—	T2IE	—	—	—	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0096	—	—	INT2IE	—	—	—	—	—	—	—	—	INT1IE	CNIE	AC1IE	MI2C1IE	SI2C1IE	0000
IEC3	009A	—	—	—	—	—	—	PSEMIE	—	—	—	—	—	—	—	—	—	0000
IEC4	009C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	U1EIE	—	0000
IEC5	009E	PWM2IE	PWM1IE	—	—	—	—	—	—	—	—	—	—	—	—	—	JTAGIE	0000
IEC6	00A0	ADCP1IE	ADCP0IE	—	—	—	—	—	—	AC2IE	—	—	—	—	—	—	—	0000
IEC7	00A2	—	—	—	—	—	—	—	—	—	—	—	ADCP6IE	—	—	—	ADCP2IE	0000
IPC0	00A4	—	T1IP<2:0>			—	OC1IP<2:0>			—	IC1IP<2:0>			—	INT0IP<2:0>			4444
IPC1	00A6	—	T2IP<2:0>			—	—	—	—	—	—	—	—	—	—	—	—	4000
IPC2	00A8	—	U1RXIP<2:0>			—	SPI1IP<2:0>			—	SPI1EIP<2:0>			—	—	—	—	4440
IPC3	00AA	—	—	—	—	—	—	—	—	—	ADIP<2:0>			—	U1TXIP<2:0>			0044
IPC4	00AC	—	CNIP<2:0>			—	AC1IP<2:0>			—	MI2C1IP<2:0>			—	SI2C1IP<2:0>			4444
IPC5	00AE	—	—	—	—	—	—	—	—	—	—	—	—	—	INT1IP<2:0>			0004
IPC7	00B2	—	—	—	—	—	—	—	—	—	INT2IP<2:0>			—	—	—	—	0040
IPC14	00C0	—	—	—	—	—	—	—	—	—	PSEMIP<2:0>			—	—	—	—	0040
IPC16	00C4	—	—	—	—	—	—	—	—	—	U1EIP<2:0>			—	—	—	—	0040
IPC20	00CC	—	—	—	—	—	—	—	—	—	—	—	—	—	JTAGIP<2:0>			0004
IPC23	00D2	—	PWM2IP<2:0>			—	PWM1IP<2:0>			—	—	—	—	—	—	—	—	4400
IPC25	00D6	—	AC2IP<2:0>			—	—	—	—	—	—	—	—	—	—	—	—	4000
IPC27	00DA	—	ADCP1IP<2:0>			—	ADCP0IP<2:0>			—	—	—	—	—	—	—	—	4400
IPC28	00DC	—	—	—	—	—	—	—	—	—	—	—	—	—	ADCP2IP<2:0>			0004
IPC29	00DE	—	—	—	—	—	—	—	—	—	—	—	—	—	ADCP6IP<2:0>			0004
INTTREG	00E0	—	—	—	—	ILR<3:0>				—	VECNUM<6:0>							0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-39: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the File register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn forms the Effective Address (EA).
Register Indirect Post-Modified	The contents of Wn forms the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

4.4.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions and the DSP accumulator class of instructions provide a greater degree of addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

Note: For the MOV instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (register offset) field is shared by both source and destination (but typically only used by one).

In summary, the following addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-modified
- Register Indirect Pre-modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-Bit Literal
- 16-Bit Literal

Note: Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.4.4 MAC INSTRUCTIONS

The dual source operand DSP instructions (CLR, ED, EDAC, MAC, MPY, MPY.N, MOVSAC and MSC), also referred to as MAC instructions, use a simplified set of addressing modes to allow the user application to effectively manipulate the data pointers through register indirect tables.

The two-source operand prefetch registers must be members of the set {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU, and W10 and W11 are always directed to the Y AGU. The Effective Addresses generated (before and after modification) must, therefore, be valid addresses within X data space for W8 and W9 and Y data space for W10 and W11.

Note: Register Indirect with Register Offset Addressing mode is available only for W9 (in X space) and W11 (in Y space).

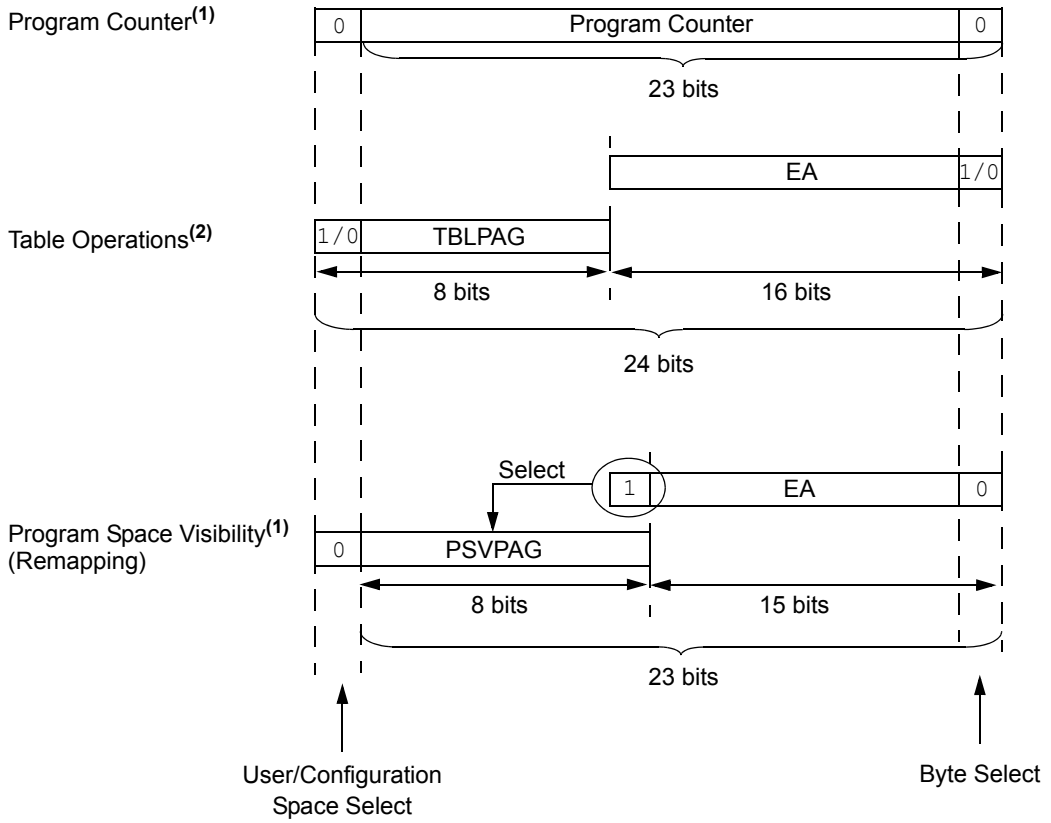
In summary, the following addressing modes are supported by the MAC class of instructions:

- Register Indirect
- Register Indirect Post-modified by 2
- Register Indirect Post-modified by 4
- Register Indirect Post-modified by 6
- Register Indirect with Register Offset (Indexed)

4.4.5 OTHER INSTRUCTIONS

Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, BRA (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the DISI instruction uses a 14-bit unsigned literal field. In some instructions, such as ADD Acc, the source of an operand or result is implied by the opcode itself. Certain operations, such as NOP, do not have any operands.

FIGURE 4-8: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



Note 1: The Least Significant bit (LSb) of program space addresses is always fixed as '0' to maintain word alignment of data in the program and data spaces.

2: Table operations are not required to be word-aligned. Table read operations are permitted in the configuration memory space.

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1) (CONTINUED)

bit 1 **BOR:** Brown-out Reset Flag bit
1 = A Brown-out Reset has occurred
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

REGISTER 7-6: IFS1: INTERRUPT FLAG STATUS REGISTER 1

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	INT2IF	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	INT1IF	CNIF	AC1IF(1	MI2C1IF	SI2C1IF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **INT2IF:** External Interrupt 2 Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 12-5 **Unimplemented:** Read as '0'

bit 4 **INT1IF:** External Interrupt 1 Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 3 **CNIF:** Input Change Notification Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 2 **AC1IF:** Analog Comparator 1 Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 1 **MI2C1IF:** I2C1 Master Events Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **SI2C1IF:** I2C1 Slave Events Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

Note 1: This bit is not implemented in dsPIC33FJ06GS101A/102A devices.

10.9 Peripheral Pin Select Registers

The following registers are implemented for remappable peripheral configuration:

- 15 Input Remappable Peripheral Registers
- 19 Output Remappable Peripheral Registers

Note: Input and output register values can only be changed if IOLOCK (OSCCON<6>) = 0. See **Section 10.6.3.1 "Control Register Lock"** for a specific command sequence.

Not all Output Remappable Peripheral registers are implemented on all devices. See the register description of the specific register for further details.

REGISTER 10-1: RPINR0: PERIPHERAL PIN SELECT INPUT REGISTER 0

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	INT1R<5:0>					
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **INT1R<5:0>:** Assign External Interrupt 1 (INTR1) to the Corresponding RPn Pin bits

111111 = Input tied to Vss
100011 = Input tied to RP35
100010 = Input tied to RP34
100001 = Input tied to RP33
100000 = Input tied to RP32
•
•
•
00000 = Input tied to RP0

bit 7-0 **Unimplemented:** Read as '0'

REGISTER 15-2: PTCON2: PWM CLOCK DIVIDER SELECT REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	PCLKDIV<2:0>(1)		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as ‘0’

bit 2-0 **PCLKDIV<2:0>:** PWM Input Clock Prescaler (Divider) Select bits(1)

111 = Reserved
110 = Divide-by-64, maximum PWM timing resolution
101 = Divide-by-32, maximum PWM timing resolution
100 = Divide-by-16, maximum PWM timing resolution
011 = Divide-by-8, maximum PWM timing resolution
010 = Divide-by-4, maximum PWM timing resolution
001 = Divide-by-2, maximum PWM timing resolution
000 = Divide-by-1, maximum PWM timing resolution (power-on default)

Note 1: These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

REGISTER 15-3: PTPER: PWM MASTER TIME BASE REGISTER(1)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
PTPER <15:8>							
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0
PTPER <7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **PTPER<15:0>:** PWM Master Time Base (PMTMR) Period Value bits

Note 1: The minimum value that can be loaded into the PTPER register is 0x0010 and the maximum value is 0xFFF8.

16.1 SPI Helpful Tips

1. In Frame mode, if there is a possibility that the master may not be initialized before the slave:
   a) If FRMPOL (SPIxCON2<13>) = 1, use a pull-down resistor on SSx.
   b) If FRMPOL = 0, use a pull-up resistor on SSx.

Note:	This insures that the first frame transmission after initialization is not shifted or corrupted.

2. In Non-Framed 3-Wire mode, (i.e., not using SSx from a master):
   a) If CKP (SPIxCON1<6>) = 1, always place a pull-up resistor on SSx.
   b) If CKP = 0, always place a pull-down resistor on SSx.

Note:	This will insure that during power-up and initialization the master/slave will not lose Sync due to an errant SCK transition that would cause the slave to accumulate data shift errors for both transmit and receive appearing as corrupted data.

3. FRMEN (SPIxCON2<15>) = 1 and SSEN (SPIxCON1<7>) = 1 are exclusive and invalid. In Frame mode, SCKx is continuous and the Frame Sync pulse is active on the SSx pin, which indicates the start of a data frame.

Note:	Not all third-party devices support Frame mode timing. Refer to the SPI electrical characteristics for details.

4. In Master mode only, set the SMP bit (SPIxCON1<9>) to a '1' for the fastest SPI data rate possible. The SMP bit can only be set at the same time or after the MSTEN bit (SPIxCON1<5>) is set.

To avoid invalid slave read data to the master, the user's master software must ensure enough time for slave software to fill its write buffer before the user application initiates a master write/read cycle. It is always advisable to preload the SPIxBUF Transmit register in advance of the next master transaction cycle. SPIxBUF is transferred to the SPI Shift register and is empty once the data transmission begins.

16.2 SPI Resources

Many useful resources related to SPI are provided on the Microchip web site (www.microchip.com).

16.2.1 KEY RESOURCES

- **Section 18. "Serial Peripheral Interface (SPI)"** (DS70206)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related *"dsPIC33F/PIC24H Family Reference Manual"* Sections
- Development Tools

REGISTER 19-7: ADCPC3: ADC CONVERT PAIR CONTROL REGISTER 3(1) (CONTINUED)

bit 4-0 **TRGSRC6<4:0>:** Trigger 6 Source Selection bits

Selects trigger source for conversion of analog channels AN13 and AN12.

11111 = Timer2 period match
•
•
•
11011 = Reserved
11010 = PWM Generator 4 current-limit ADC trigger
11001 = Reserved
11000 = PWM Generator 2 current-limit ADC trigger
10111 = PWM Generator 1 current-limit ADC trigger
10110 = Reserved
•
•
•
10010 = Reserved
10001 = PWM Generator 4 secondary trigger is selected
10000 = Reserved
01111 = PWM Generator 2 secondary trigger is selected
01110 = PWM Generator 1 secondary trigger is selected
01101 = Reserved
01100 = Timer1 period match
•
•
•
01000 = Reserved
00111 = PWM Generator 4 primary trigger is selected
00110 = Reserved
00101 = PWM Generator 2 primary trigger is selected
00100 = PWM Generator 1 primary trigger is selected
00011 = PWM Special Event Trigger is selected
00010 = Global software trigger is selected
00001 = Individual software trigger is selected
00000 = No conversion is enabled

Note 1: If other conversions are in progress, conversion will be performed when the conversion resources are available.

2: AN13 is internally connected to Vref in all devices. AN12 is internally connected to the EXTREF pin in the dsPIC33FJ06001/202A and dsPIC33FJ09GS302 devices. The dsPIC33FJ06GS101A/102A devices not have an EXTREF pin; therefore, any data read on the corresponding AN12 input will be invalid.

REGISTER 20-1: CMPCONx: COMPARATOR CONTROL x REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CMPON(1)	—	CMPSIDL(1)	HYSSEL<1:0>(1)		FLTREN(1)	FCLKSEL(1)	DACOE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INSEL<1:0>(1)		EXTREF(1)	HYSPOL(1)	CMPSTAT(1)	HGAIN(1)	CMPPOL(1)	RANGE(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CMPON:** Comparator Operating Mode bit(1)
1 = Comparator module is enabled
0 = Comparator module is disabled (reduces power consumption)

bit 14 **Unimplemented:** Read as '0'

bit 13 **CMPSIDL:** Stop in Idle Mode bit(1)
1 = Discontinues module operation when device enters Idle mode.
0 = Continues module operation in Idle mode
If a device has multiple comparators, any CMPSIDL bit that is set to '1' disables *all* comparators while in Idle mode.

bit 12-11 **HYSSEL<1:0>:** Comparator Hysteresis Select bits(1)
11 = 45 mV hysteresis
10 = 30 mV hysteresis
01 = 15 mV hysteresis
00 = No hysteresis is selected

bit 10 **FLTREN:** Digital Filter Enable bit(1)
1 = Digital filter is enabled
0 = Digital filter is disabled

bit 9 **FCLKSEL:** Digital Filter and Pulse Stretcher Clock Select bit(1)
1 = Digital filter and pulse stretcher operate with the PWM clock
0 = Digital filter and pulse stretcher operate with the system clock

bit 8 **DACOE:** DAC Output Enable(1)
1 = DAC analog voltage is output to DACOUT pin(2)
0 = DAC analog voltage is not connected to DACOUT pin

bit 7-6 **INSEL<1:0>:** Input Source Select for Comparator bits(1)
11 = Select CMPxD input pin
10 = Select CMPxC input pin
01 = Select CMPxB input pin
00 = Select CMPxA input pin

Note 1: This bit is not implemented in dsPIC33FJ06GS101A/102A devices.

2: DACOUT can be associated only with a single comparator at any given time. The software must ensure that multiple comparators do not enable the DAC output by setting their respective DACOE bit.

3: For the INTREF value, refer to the DAC Module Specifications (Table 25-42) in **Section 25.0 "Electrical Characteristics"**.

TABLE 25-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param.	**Typical(1)**	**Max.**	**Units**	**Conditions**		
Power-Down Current (I_{PD})(2,4)						
DC60d	125	500	μA	-40°C	3.3V	Base Power-Down Current
DC60a	135	500	μA	+25°C		
DC60b	235	500	μA	+85°C		
DC60c	565	950	μA	+125°C		
DC61d	40	50	μA	-40°C	3.3V	Watchdog Timer Current: ΔI_{WDT}(3)
DC61a	40	50	μA	+25°C		
DC61b	40	50	μA	+85°C		
DC61c	80	90	μA	+125°C		

Note 1: Data in the Typical column is at 3.3V, +25°C unless otherwise stated.

2: I_{PD} current is measured as follows:

- CPU core is off, oscillator is configured in EC mode, OSC1 is driven with external square wave from rail-to-rail
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all '1's)
- VREGS bit (RCON<8>) = 1 (i.e., core regulator is set to standby while the device is in Sleep mode)

3: The Δ current is the additional current consumed when the WDT module is enabled. This current should be added to the base I_{PD} current.

4: These currents are measured on the device containing the most memory in this family.

TABLE 25-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 4x Sink Driver Pins – RA0-RA2, RB0-RB2, RB5-RB10, RB15	—	—	0.4	V	IOL ≤ 6 mA, VDD = 3.3V**(1)**
		Output Low Voltage I/O Pins: 16x Sink Driver Pins – RA3, RA4, RB3, RB4, RB11-RB14	—	—	0.4	V	IOL ≤ 18 mA, VDD = 3.3V**(1)**
DO20	VOH	**Output High Voltage** I/O Pins: 4x Source Driver Pins – RA0-RA2, RB0-RB2, RB5-RB10, RB15	2.4	—	—	V	IOH ≥ -6 mA, VDD = 3.3V**(1)**
		Output High Voltage I/O Pins: 16x Source Driver Pins – RA3, RA4, RB3, RB4, RB11-RB14	2.4	—	—	V	IOH ≥ -18 mA, VDD = 3.3V**(1)**
DO20A	VOH1	**Output High Voltage** I/O Pins: 4x Source Driver Pins – RA0-RA2, RB0-RB2, RB5-RB10, RB15	1.5	—	—	V	IOH ≥ -12 mA, VDD = 3.3V**(1)**
			2.0	—	—		IOH ≥ -11 mA, VDD = 3.3V**(1)**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V**(1)**
		Output High Voltage I/O Pins: 16x Source Driver Pins – RA3, RA4, RB3, RB4, RB11-RB14	1.5	—	—	V	IOH ≥ -30 mA, VDD = 3.3V**(1)**
			2.0	—	—		IOH ≥ -25 mA, VDD = 3.3V**(1)**
			3.0	—	—		IOH ≥ -8 mA, VDD = 3.3V**(1)**

Note 1: These parameters are characterized, but not tested.

TABLE 25-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V**(3)** (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.(1)**	**Typ.**	**Max.**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD Transition High-to-Low BOR Event is Tied to VDD Core Voltage Decrease	2.55	—	2.96	V	(See **Note 2**)

Note 1: These parameters are for design guidance only and are not tested in manufacturing.

2: The device will operate as normal until the VDDMIN threshold is reached.

3: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested but not characterized. All device analog modules, such as the ADC, etc., will function but with degraded performance below VDDMIN.

TABLE 25-33: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**
SP60	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCKx clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 25-37: I2C1 BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param.	**Symbol**	**Characteristic**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM20	TF:SCL	SDA1 and SCL1 Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 pF to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDA1 and SCL1 Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 pF to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	0.2	—	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(2)	—	400	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	0.5	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	See **Note 3**

Note 1: BRG is the value of the I^2C™ Baud Rate Generator. Refer to **Section 19. "Inter-Integrated Circuit (I^2C™)"** (DS70195) in the "*dsPIC33F/PIC24H Family Reference Manual*".

2: Maximum pin capacitance = 10 pF for all I2C1 pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

TABLE 25-43: DAC OUTPUT (DACOUT PIN) DC SPECIFICATIONS

DC CHARACTERISTICS(1)			Standard Operating Conditions (unless otherwise stated) Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DA11	RLOAD	Resistive Output Load Impedance	3K	—	—	Ohm	
—	CLOAD	Output Load Capacitance	—	—	35	pF	Including output pin capacitance
DA12	IOUT	Output Current Drive Strength	200	300	—	µA	Sink and source
DA13	VRANGE	Output Drive Voltage Range at Current Drive of 200 mA	AVSS + 250 mV	—	AVDD – 900 mV	V	
DA14	VLRANGE	Output Drive Voltage Range at Reduced Current Drive of 50 mA	AVSS + 5 mV	—	AVDD – 500 mV	V	
DA15	IDD	Current Consumed when Module Is Enabled	—	—	1.3 x IOUT	µA	Module will always consume this current even if no load is connected to the output
DA16	ROUTON	Output Impedance when Module is Enabled	—	820	—	Ohms	
DA30	VOFFSET	Input Offset Voltage	—	±10	10	mV	

Note 1: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested but not characterized. All device analog modules, such as the ADC, etc., will function but with degraded performance below VDDMIN. Refer to Parameter BO10 in Table 25-11 for BOR values.

TABLE 25-44: DAC GAIN STAGE TO COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS(1)			Standard Operating Conditions (unless otherwise stated) Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DA15	IDD	Current Consumed when Module Is Enabled.	—	60	—	µA	Module will always consume this current even if no load is connected to the output
DA32	G	Amplifier Gain	—	1.0	—	—	
			—	1.8	—	—	
DA33	GBWP	Gain Bandwidth Product	—	2.0	—	MHz	At 1 pF load capacitance. Measured with sine wave output signal of 1V peak-to-peak with a midpoint value of 1.2V. Voltage excursion from 0.7 to 1.7V.
DA34	SR	Slew Rate	—	5	—	V/µs	Slew rate between 10% and 90% of AVDD
DA07	TS	Settling Time	—	200	—	ns	Settling time to 3%

Note 1: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested but not characterized. All device analog modules, such as the ADC, etc., will function but with degraded performance below VDDMIN. Refer to Parameter BO10 in Table 25-11 for BOR values.

26.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 26-1: VOH – 4x DRIVER PINS

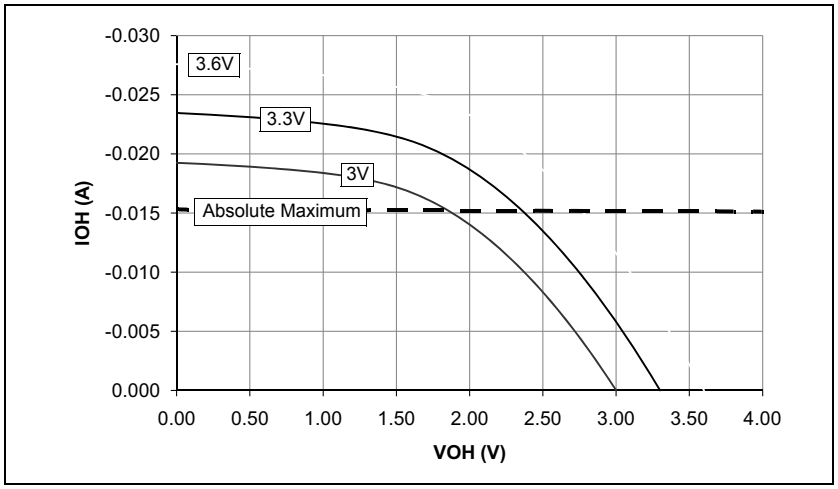


FIGURE 26-2: VOH – 16x DRIVER PINS

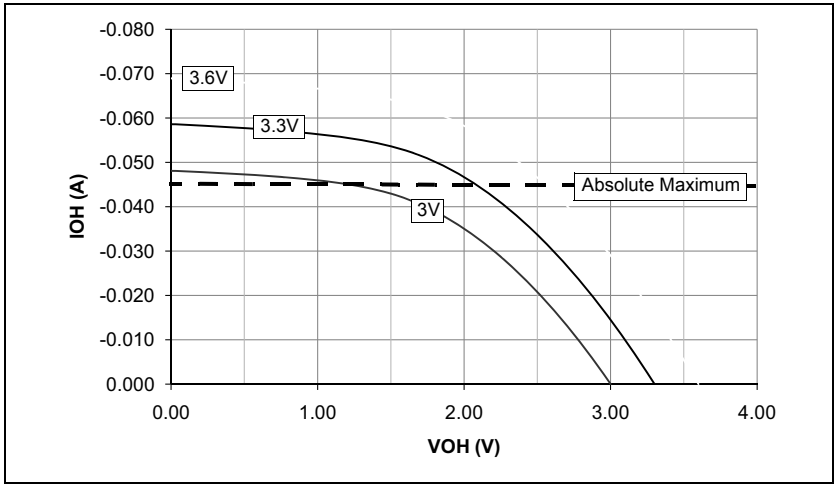


FIGURE 26-3: VOL – 4x DRIVER PINS

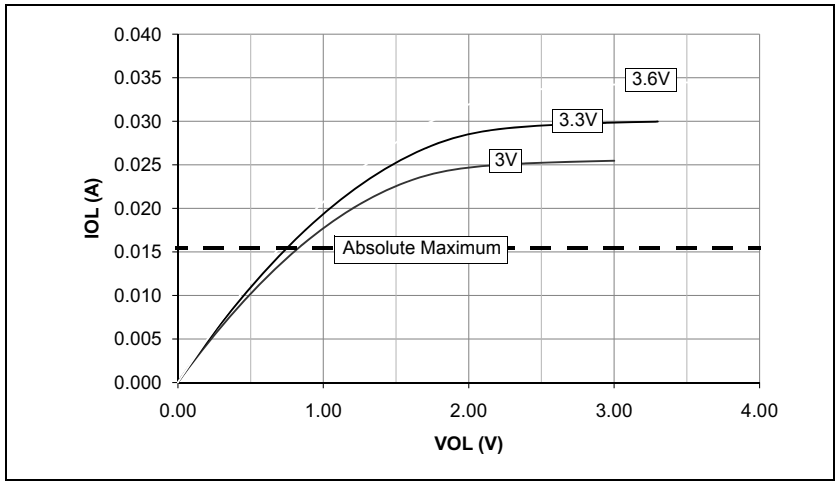
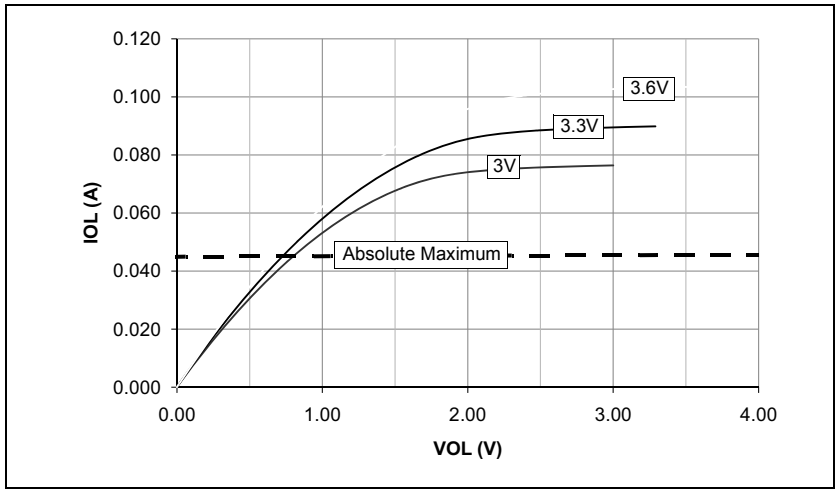
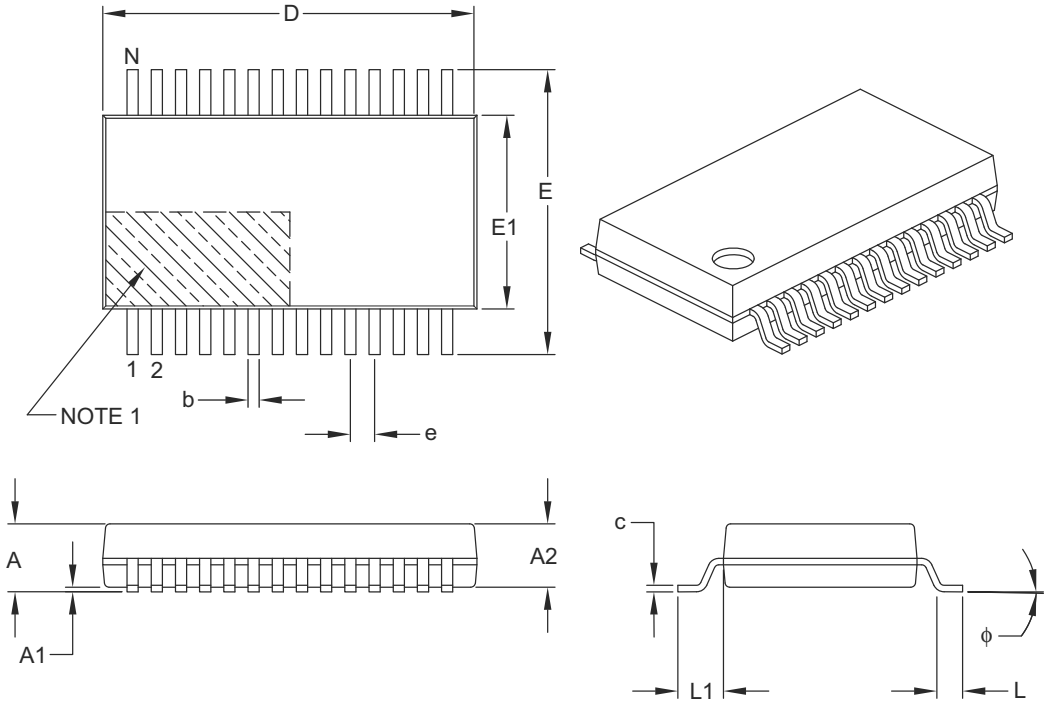


FIGURE 26-4: VOL – 16x DRIVER PINS



28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

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